



Product Specification

Part Name: 5.94 inch TFT Display Module

Customer Part ID:

Topovision Part ID: TVT0600A2-CP

Ver: A

Customer:
Approved by

From: Topovision Technology Co., Ltd.
Approved by

Notes:

1. Please contact Topovision Technology Co., Ltd. before assigning your product based on this module specification
2. The information contained herein is presented merely to indicate the characteristics and performance of our products. No responsibility is assumed by Topovision Technology Co., Ltd. for any intellectual property claims or other problems that may result from application based on the module described herein.

1. Introduction

1.1 Scope of application

This specification applies to the LCD module that is supplied by Topovision Technology CO., LTD.

LCD specification: Dots 720xRGBx1280

As to basic specification of the driver IC, refer to the IC (**Raydium:RM68200**) specification and data book.

All material & processing of the LCD module should be Lead Free.

1.2 TFT features:

TFT Structure: TFT PANNEL+IC +FPC+BL;

TP Structure: G+F+F

IPS Type LCD

720dot-segment and 1280 dot-common outputs;

16.7M Color can be selected by software;

White LED back light;

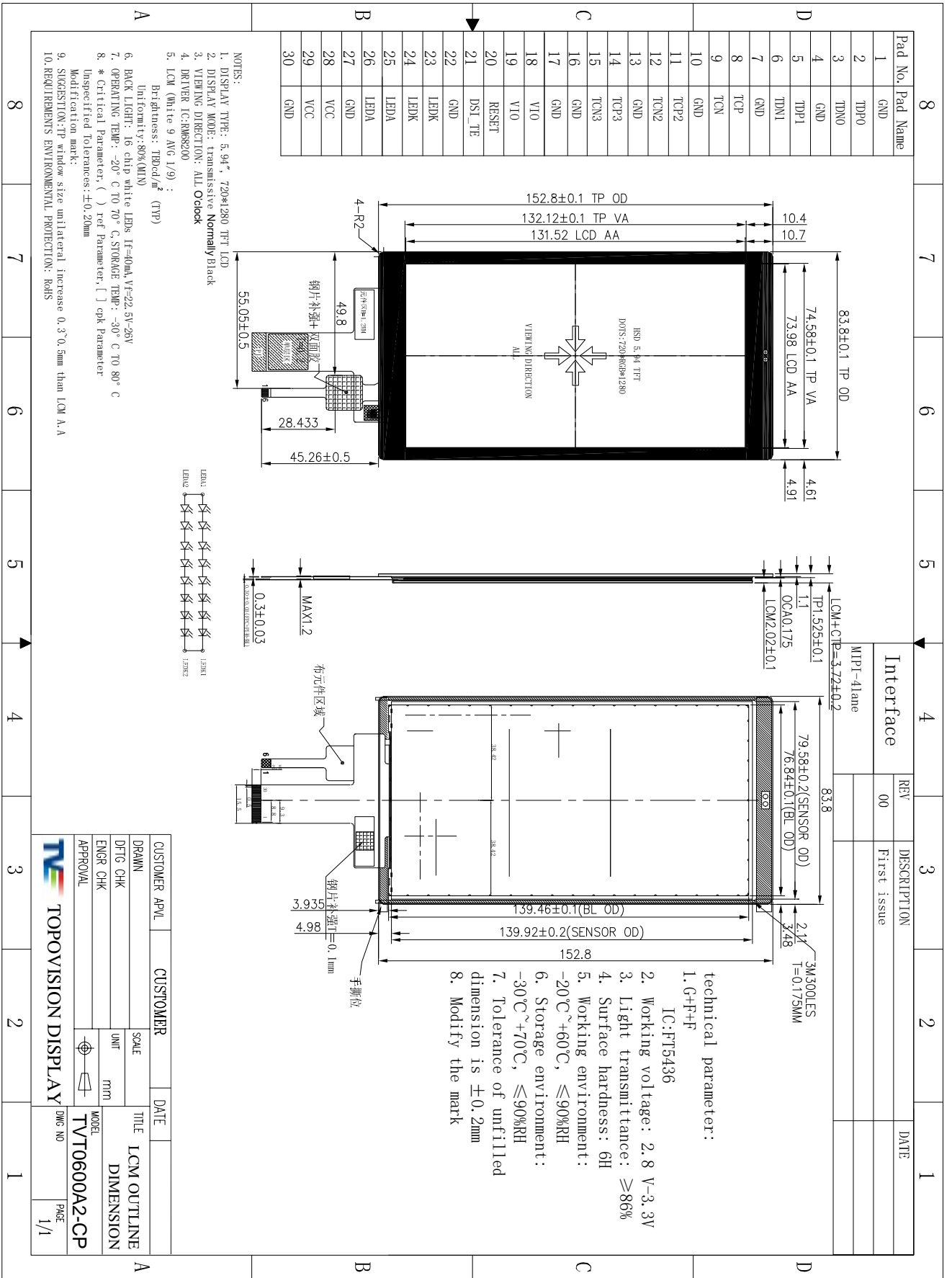
TFT interface: MIPI-4lane

TP interface: I2C

1.3 Applications:

2. LCM General specification

ITEM	Standard value	Unit
LCD Type	Normally black	--
Drive element	TFT active matrix	--
Number of pixels	720*3RGB(H)X1280(V)	Dots
Pixel arrangement	RGB stripe	--
Pixel Pitch (W*H)	0.10275(W) × 0.10275 (H)	mm
Active area	73.98(W) × 131.52(H)	mm
Viewing direction	ALL O'CLOCK	-
TFT Driver IC	RM68200	
TFT interface	MIPI 4Lane	-
TFTModule Size(W*H*T)	76.84(W) × 139.46(H) × 2.02(D)	mm
Approx. Weight	TBD	g
Touch structure	G+F+F	
Touch Driver IC	FT5436	-
Touch Interface	I2C	
TP Module Size(W*H*T)	83.3(W) × 152.8(H) × 3.72(D)	



3. Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit
LCM Operating Temperature	T _{OPR}	-20	+70	°C
LCM Storage Temperature	T _{STG}	-30	+80	°C
TP Operating Temperature & Humidity(20% ~ 90%RH)	T _{OPR}	-20	+70	°C
TP SStorage Temperature & Humidity(20% ~ 90%RH)	T _{STG}	-30	+80	°C
Humidity	RH	-	90	%

4. Electrical Characteristics

4.1.1 TFT DC Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage for I/O	VDDIO	1.65	1.8	3.3	V
Supply Voltage for(DC/DC)	VDD	2.5	2.8	3.6	V
Supply Voltage for(DC/DC)	AVDD				V
Supply Voltage for(DC/DC)	AVEE				V
Current Consumption	I _{DD}	-	TBD	-	mA
	I _{DD-SLEEP}		TBD		uA

4.1.2 Touch Electric Characteristics

项目 Items	值 Value
工作电压Working voltage	DC2.8~ 3.3V
绝缘阻抗Insulation Resistance	> 20M
工作电流Working current	12mA~14.5mA
响应时间Response time	≤16ms

4.2 Back-Light Unit Characteristics

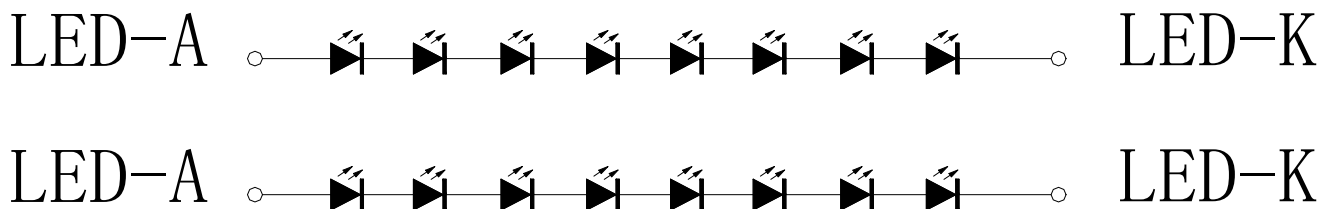
The back-light system is an edge-lighting type with 16 white LEDs. The characteristics of the back-light are shown in the following tables.

Characteristics	Symbol	Min.	Type	Max.	Unit	Notes
Forward Voltage	V_F	22.5	--	26	V	-
Forward current	I_F	--	40	-	mA	-
Luminance(With LCD)	L_v		300	--	cd/m ²	-
LED life time	N/A	----	30,000	--	Hr	Note 1

Note:

- (1) The “LED life time” is defined as the module brightness decrease to 50% of original brightness at $I_L=20\text{mA/LED}$. The LED life time could be decreased if operating I_L is larger than 25mA/LED.

Backlight circuit diagram shown in below:



5. Module Function Description

Pin No.	Symbol	Functional	Notes
1	GND	Power Ground	
2	TDP0	MIPI DSI differential data pair	
3	TDN0		
4	GND	Power Ground	
5	TDP1	MIPI DSI differential data pair	
6	TDN1		
7	GND	Power Ground	
8	TCP	MIPI DSI differential clock pair	
9	TCN		
10	GND	Power Ground	
11	TDP2	MIPI DSI differential data pair	

12	TDN2		
13	GND	Power Ground	
14	TDP3	MIPI DSI differential data pair	
15	TDN3		
16	GND	Power Ground	
17	GND	Power Ground	
18	IOVCC	I/O Voltage (VDDI to DGND): 1.65V ~ 3.3V	
19	IOVCC	I/O Voltage (VDDI to DGND): 1.65V ~ 3.3V	
20	RESET	Reset signal input terminal. Active at 'L'.	
21	TE	Tearing effect output pin to synchronize MPU to frame writing	
22	GND	Power Ground	
23	LEDK	Power supply for backlight cathode input terminal.	
24	LEDK	Power supply for backlight cathode input terminal.	
25	LEDA	Power supply for backlight anode input terminal.	
26	LEDA	Power supply for backlight anode input terminal.	
27	GND	Power Ground	
28	VCC	MIPI Voltage (VDDAM to VSSAM): 2.5V ~ 3.6V	
29	VCC	MIPI Voltage (VDDAM to VSSAM): 2.5V ~ 3.6V	
30	GND	Power Ground	

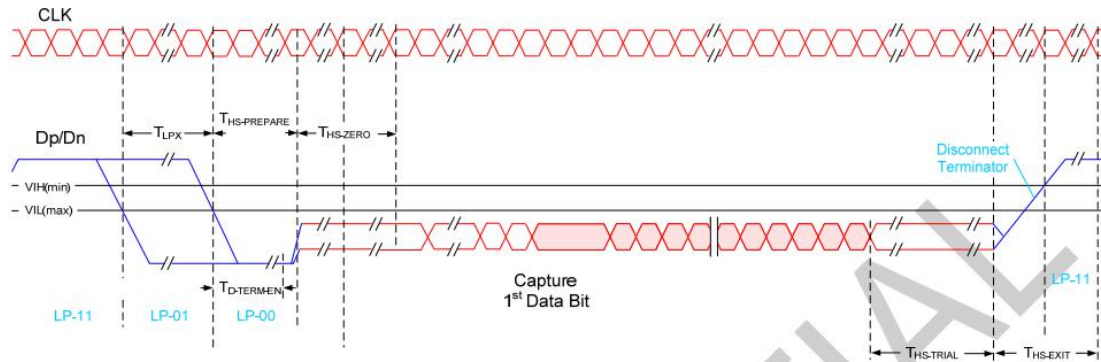
TP Pin Descriptions

NO:	SYMBOL	I/O	FUNCTION
1	SCL	I/O	Touch panel I2C clock
2	SDA	I/O	Touch panel I2C data
3	GND	P	Ground
4	RST	I/O	Touch panel reset
5	INT	I/O	Touch panel interrupt output
6	VDD	P	Touch panel I/O PWR supply

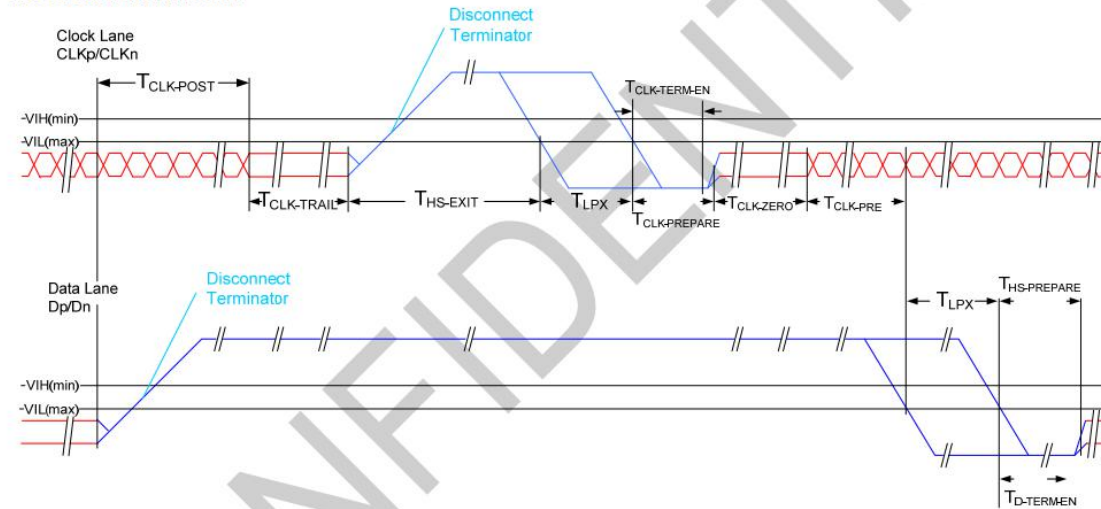
6. Timing Characteristics

9.5.4 DSI Timing Characteristics

HS Data Transmission Burst

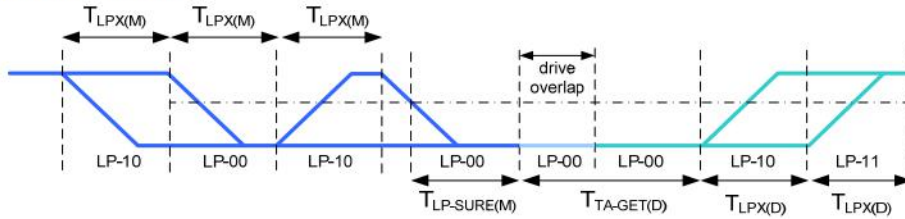
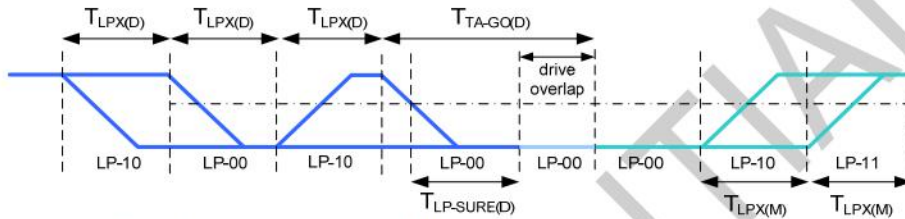


HS clock transmission



Timing Parameters:

Parameter	Description	Min	Typ	Max	Unit
$T_{CLK-POST}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS-TRAIL}$ to the beginning of $T_{CLK-TRAIL}$.	$60ns + 52*UI$			ns
$T_{CLK-TRAIL}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns
$T_{HS-EXIT}$	Time that the transmitter drives LP-11 following a HS burst.	300			ns
$T_{CLK-TERM-EN}$	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{IL,MAX}$.	Time for Dn to reach $V_{TERM-EN}$		38	ns
$T_{CLK-PREPARE}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns
$T_{CLK-PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8			UI
$T_{CLK-PREPARE} + T_{CLK-ZERO}$	$T_{CLK-PREPARE}$ + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns
$T_{D-TERM-EN}$	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses $V_{IL,MAX}$.	Time for Dn to reach $V_{TERM-EN}$		$35 ns + 4*UI$	
$T_{HS-PREPARE}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	$40ns + 4*UI$		$85 ns + 6*UI$	ns
$T_{HS-PREPARE} + T_{HS-ZERO}$	$T_{HS-PREPARE}$ + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	$145ns + 10*UI$			ns
$T_{HS-TRAIL}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	$60ns + 4*UI$			ns

Turnaround Procedure

Bus turnaround (BAT) from MPU to display module timing

Bus turnaround (BAT) from display module to MPU timing
Low Power Mode:

Parameter	Description	Min	Typ	Max	Unit	Notes
$T_{LPX(M)}$	Transmitted length of any Low-Power state period of MCU to display module	50		150	ns	1,2
$T_{TA-SURE(M)}$	Time that the display module waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(M)}$		$2 * T_{LPX(M)}$	ns	2
$T_{LPX(D)}$	Transmitted length of any Low-Power state period of display module to MCU	50		150	ns	1,2
$T_{TA-GET(D)}$	Time that the display module drives the Bridge state (LP-00) after accepting control during a Link Turnaround.		$5 * T_{LPX(D)}$		ns	2
$T_{TA-GO(D)}$	Time that the display module drives the Bridge state (LP-00) before releasing control during a Link Turnaround.		$4 * T_{LPX(D)}$		ns	2
$T_{TA-SURE(D)}$	Time that the MPU waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	$T_{LPX(D)}$		$2 * T_{LPX(D)}$	ns	2

NOTE:

- T_{LPX} is an internal state machine timing reference. Externally measured values may differ slightly from the specified values due to asymmetrical rise and fall times.
- Transmitter-specific parameter

7. Optical Characteristics

Items	Symbol	Condition	Specifications			Unit
			Min.	Typ.	Max.	
Contrast Ratio	CR		-	800	-	-
Response Time	$T_R + T_F$		-	35	-	ms
			-	-	-	ms
Chromaticity	Red	X_R		/		-
		Y_R		/		-
	Green	X_G		/		-
		Y_G		/		-

	Blue	X_B		/		-	
		Y_B		/		-	
	White	X_W		0.28	0.31	0.34	-
		Y_W		0.29	0.32	0.35	-
Viewing angle	Hor.	$\phi 1$ (3 o'clock)	Center $CR \geq 10$	-	80	-	g.
		$\phi 2$ (9 o'clock)		-	80	-	
	Ver.	$\theta 2$ (12 o'clock)		-	80	-	
		$\theta 1$ (6 o'clock)		-	80	-	
Uniformity				--		%	

Note 1: Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{63} / L_0$$

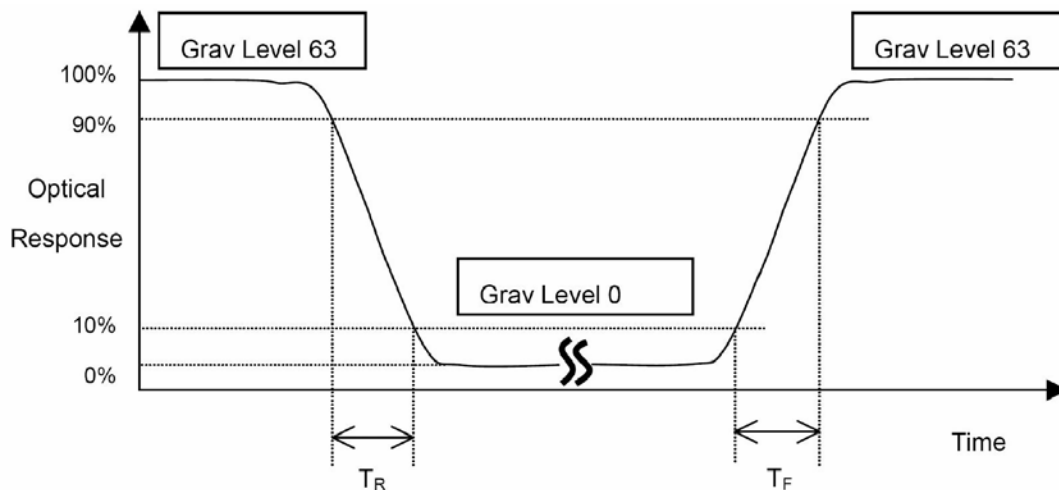
L63: Luminance of gray level 63

L0: Luminance of gray level 0

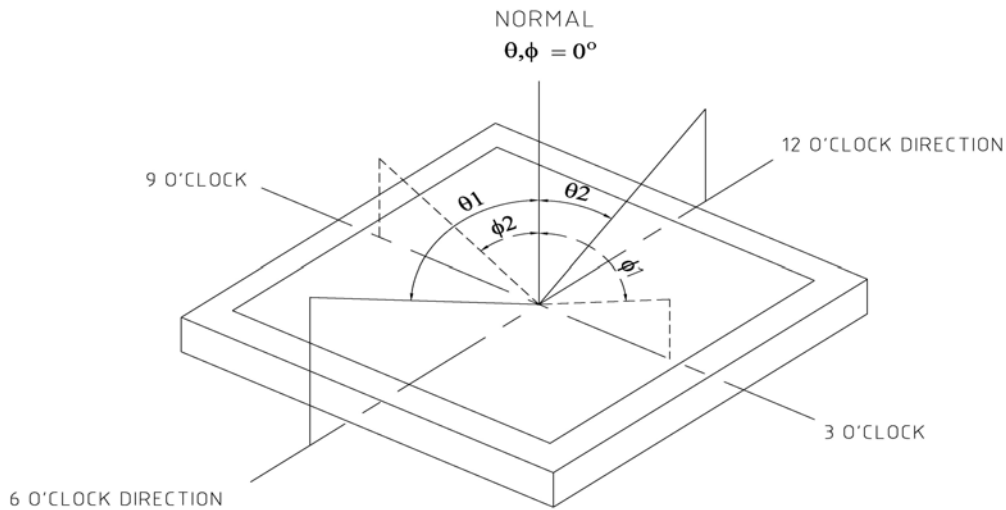
$$CR = CR(10)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note 5.

Note 2: Definition of Response Time (TR, TF):



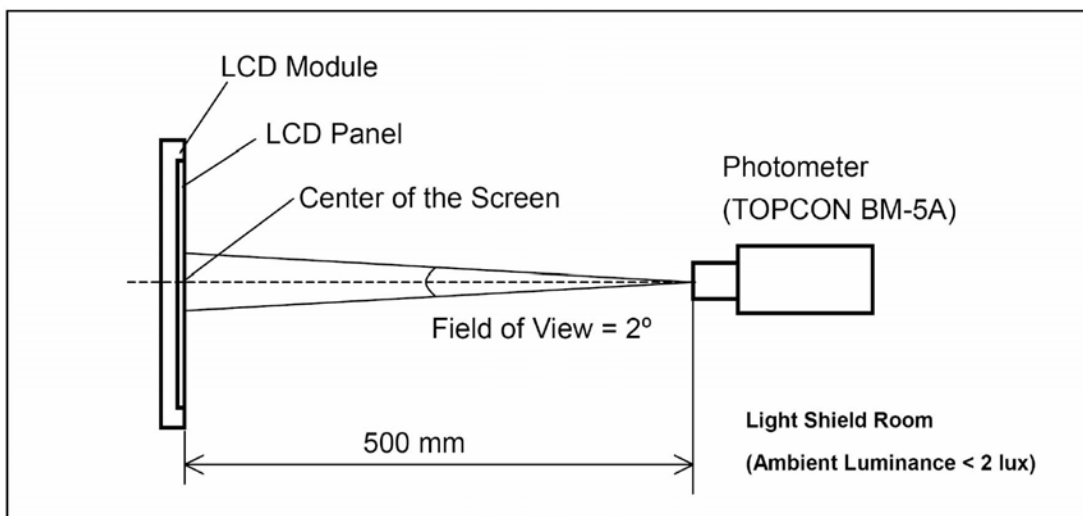
Note 3: Viewing Angle



The above “Viewing Angle” is the measuring position with Largest Contrast Ratio; not for good image quality. View Direction for good image quality is 6 O’clock. Module maker can increase the “Viewing Angle” by applying Wide View Film.

Note 4: Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.



8. Reliability Test Item

No.	Item	Conditions	Remark
1	High Temperature Storage	Ta=+80°C, 240hrs	-
2	Low Temperature Storage	Ta=-30°C, 240hrs	-
3	High Temperature Operation	Ta=+70°C, 240hrs	-
4	Low Temperature Operation	Ta=-20°C, 240hrs	-
5	High Temperature and High Humidity (Operating)	Ta=+60°C, 90%RH, 240hrs	-

Note: (1) All tests above are practiced at module type.

(2) There is no display function NG issue occurred, all the cosmetic specification is judged before the reliability stress.

9. Packing Method----TBD

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